Lam Research Ships 100th Syndion® Etch Module

FREMONT, CA -- (Marketwired) -- 10/20/14 -- Lam Research Corp.(NASDAQ: LRCX), a major global supplier of innovative wafer fabrication equipment and services to the semiconductor industry, today announced it has shipped the 100th Syndion® module for deep silicon etch applications, including CMOS image sensors (CIS), interposers, and through-silicon vias (TSVs). Lam's production-proven 2300® Syndion® product family is the etch market leader for manufacturing advanced CIS chips, which are used in mobile, automotive, and medical devices. The systems are also used to create TSVs for stacked memory and other three-dimensional integrated circuits (3D ICs). To enable the transition of 3D ICs from development to high-volume production, Lam's Syndion products provide industry-leading performance in etch uniformity, profile control, and productivity. As a result, Syndion is the development tool of record for TSV etch with the majority of leading IC manufacturers worldwide.

"We are pleased to have achieved this important milestone, which validates the trust our customers have in Syndion's capabilities, not only to address expanding CIS applications, but also to tackle tough TSV integration challenges," said Vahid Vahedi, group vice president, Etch Product Group. "Because of Syndion's broad process flexibility, we are playing a critical role in supporting the industry's transition of 3D ICs to production."

The market for Syndion's applications is growing with the increasing demand for new products that incorporate CIS devices and TSV structures. Widespread integration of CIS chips in mobile electronics -- for example, cameras in cell phones and tablets -- and for automotive and medical applications continues to fuel demand. To achieve smaller form factors and increase bandwidth for memory chips, TSVs are being integrated into manufacturing for stacked memory designs, such as those used in advanced networking systems and servers. To address requirements for faster data transfer rates, smaller package sizes, and reduced power consumption, TSVs are also being used to connect vertically stacked chips to form 3D ICs. One of the key challenges for transitioning 3D ICs to high-volume manufacturing is achieving a lower overall cost of ownership for integration.

The successful adoption of Syndion products at customers worldwide is a result of their robust design -- built on Lam's market-leading 2300® Kiyo® conductor etch family -- and their optimization for deep silicon etch applications. In particular, Syndion's fast gas switching capabilities enable the industry's highest throughput with superior etch depth and critical dimension (CD) uniformity for both large CD/low aspect ratio and small CD/high aspect ratio structures. These technologies provide the high productivity and process control needed to integrate TSVs into production environments.

About Lam Research
Lam Research Corp.(NASDAQ: LRCX) is a trusted global supplier of innovative wafer fabrication equipment and services to the semiconductor industry. Lam's broad portfolio of market-leading deposition, etch, strip, and wafer cleaning solutions helps customers achieve success on the wafer by enabling device features that are 1,000 times smaller than a grain of sand, resulting in smaller, faster, and more power-efficient chips. Through collaboration, continuous innovation, and delivering on commitments, Lam is transforming atomic-scale engineering and enabling its customers to shape the future of technology. Based in Fremont, Calif., Lam Research is an S&P 500® company whose common stock trades on the NASDAQ® Global Select Market™ under the symbol LRCX. For more information, please visit http://www.lamresearch.com. (LRCX-P)

Caution Regarding Forward-Looking Statements
Statements made in this press release that are not of historical fact are forward-looking statements and are subject to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Such forward-looking statements relate to, but are not limited to, statements concerning the performance of and demand for Lam's Syndion products, which can vary depending on process and customer application, the demand and applications for new products including semiconductors that incorporate CIS devices and TSV structures as well as products offered by Lam, the challenges affecting adoption of new technologies (such as 3D ICs) for high-volume manufacturing and the role that Lam and its customers may play in addressing those challenges. Such forward-looking statements are based on current beliefs and expectations and are subject to risks, uncertainties and changes in condition, significance, value and effect, including those discussed in Lam's annual report on Form 10-K under the heading "Risk Factors" as well as in other documents filed by Lam with the Securities and Exchange Commission. Such risks, uncertainties and changes in condition, significance, value and effect could cause actual results to differ materially from those expressed herein and in ways not readily foreseeable. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the dates made and of information reasonably known to Lam as of the dates the statements were made. We undertake no obligation to release the results of any revisions to these forward-looking statements which may be made to reflect events or circumstances which occur after the date hereof or to reflect the occurrence or effect of anticipated or unanticipated events.

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